

ABSTRACT

A printed circuit board includes a group of pads suitable to be soldered to a respective group of solder-balls of a device. Each pad of the group has a crack initiation point on its perimeter at a location where cracks in a solder-ball are anticipated to start after that solder-ball is soldered to that pad. For a pad of that group having a microvia located therein, a center of that microvia is located farther than a center of that pad from its crack initiation point. For a pad of that group having a trace merging along a portion of its perimeter, that portion does not include a vicinity of that crack initiation point.